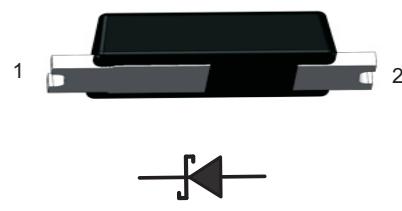


## SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

### Features

- ◆ Metal silicon junction,majority carrier conduction
- ◆ For surface mounted applications
- Metal silicon junction,majority carrier conduction
- ◆ Low power loss,high efficiency
- ◆ For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications



Top View  
Simplified outline SMAHE and symbol

### Mechanical Data

- ◆ Case : JEDEC SMAHE Molded plastic body
- ◆ Terminals : Solderable per MIL-STD-750,Method 2026
- ◆ Weight : 0.0010 ounce, 0.030grams

### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

### Mechanical Data

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

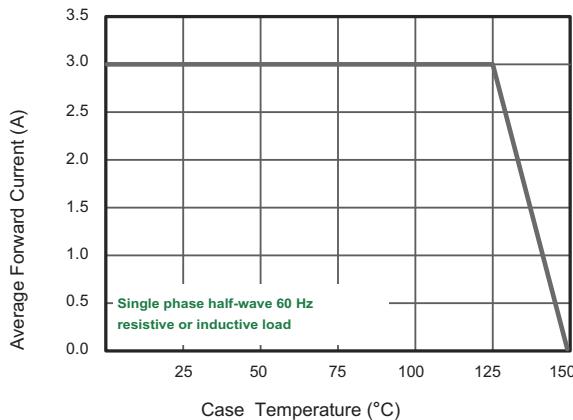
Parameter	SYMBOLS	SS34AHE	SS36AHE	SS310AHE	SS315AHE	SS320AHE	UNITS
Marking Code		MDD SS34	MDD SS36	MDD SS310	MDD SS315	MDD SS320	
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	40	60	100	150	200	V
Maximum RMS voltage	V <sub>RMS</sub>	28	42	70	105	140	V
Maximum DC blocking voltage	V <sub>DC</sub>	40	60	100	150	200	V
Maximum average forward rectified current	I <sub>F(AV)</sub>			3.0			A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I <sub>FSM</sub>			80			A
Maximum instantaneous forward voltage at 3.0A	V <sub>F</sub>	0.55	0.70	0.85	0.95		V
Maximum DC reverse current      T <sub>A</sub> =25°C at rated DCblocking voltage      T <sub>A</sub> =100°C	I <sub>R</sub>	0.5 10		0.3 5.0			mA
Typical junction capacitance (NOTE 1)	C <sub>J</sub>	180		150			pF
Typical thermal resistance (NOTE 2)	R <sub>θJA</sub>			100			°C/W
Operating junction temperature range	T <sub>J</sub>			-55 to +150			°C
Storage temperature range	T <sub>STG</sub>			-55 to +150			°C

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

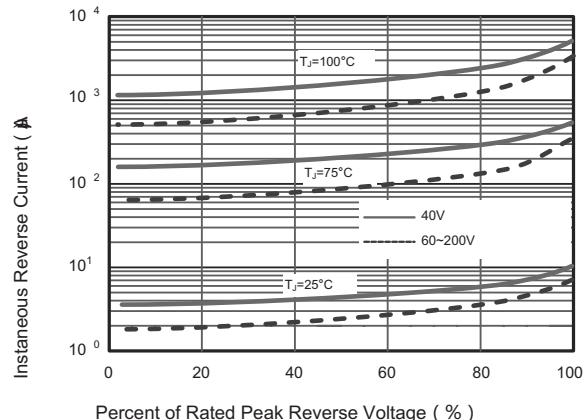
2.P.C.B. mounted with 3.81X3.81cm copper pad areas

## Typical Characteristics

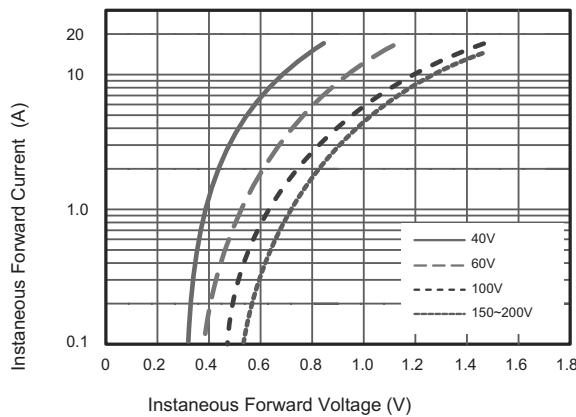
**Fig.1 Forward Current Derating Curve**



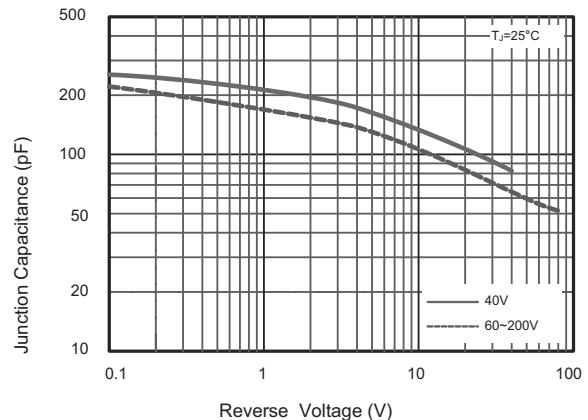
**Fig.2 Typical Reverse Characteristics**



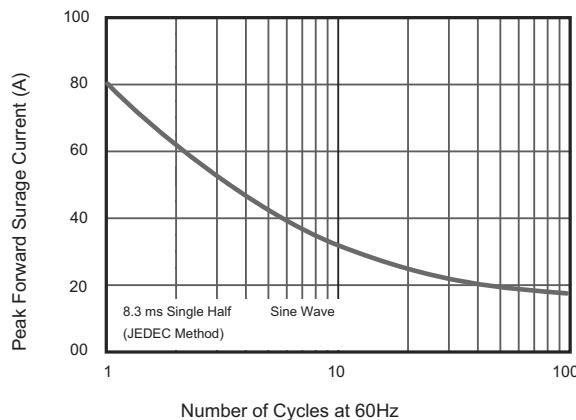
**Fig.3 Typical Forward Characteristic**



**Fig.4 Typical Junction Capacitance**

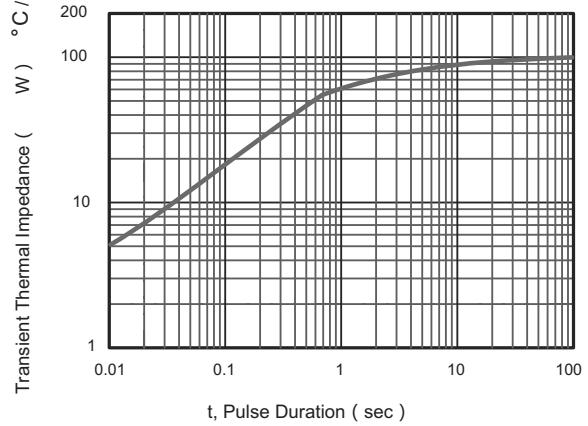


**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**

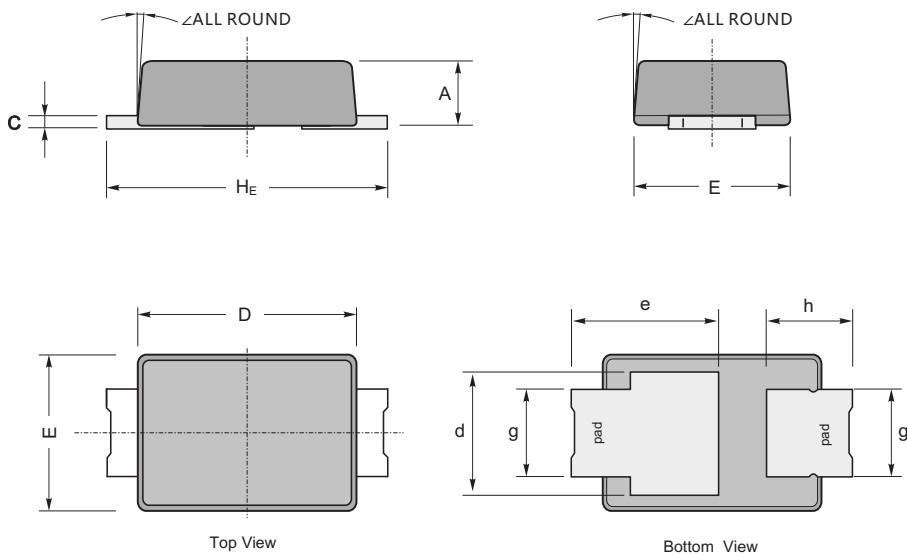


The curve above is for reference only.

**Fig.6- Typical Transient Thermal Impedance**



## Packing information



UNIT		A	C	D	E	$H_E$	d	e	g	h	$\angle$
mm	max	1.20	0.35	4.10	2.70	5.20	1.90	3.05	1.50	1.2	$12^\circ$
	min	0.90	0.20	3.70	2.30	4.80	1.70	2.85	1.30	1.0	
mil	max	47	13.8	161	106	205	75	120	59	47	$12^\circ$
	min	35	7.9	145	90	189	67	112	51	39	

### The recommended mounting pad size

